

Replacement Paragraph Page 5, Lines 1-3

A specific object of the invention is to provide for a method and an apparatus for affinity viscometry using ~~measuring, by affinity, the viscosity of~~ very small quantities of highly viscous fluids and for deriving signals thereof.

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Replacement Paragraph Page 5, Lines 9-12

In the accomplishment of these and other objects, the invention, ~~in general,~~ provides for a sensor for viscosity ~~affinity~~ measurements of in small fluid volumes without fluid consumption, and for methods of the fabrication of a viscometric ~~a miniaturized~~ sensor suitable for carrying out such measurements, including affinity viscometry.

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Replacement Paragraph Page 8, Lines 4-7

In an alternate embodiment of the invention, at least one moveable cantilevered conductor is positioned in the effective field of a permanent magnet such that the flux lines thereof extend substantially normal to the main directional movement of the conductor.

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Replacement Paragraph Page 9, Line 4

Fig. 2 is a sectional view on an enlarged scale along line II - II of Fig. 1.

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Replacement Paragraph Page 11, Lines 13-22

As regards the fabrication of the apparatus described, the structuring of the measuring zone and the movable loop 3 is significant. In accordance with the invention, the movable loop 3 is fabricated only after formation of all active and passive components of the integrated circuit of the viscosity sensor has been completed, by applying an additional photo lithographically structured ~~lacquer~~ resist mask prior to opening the ~~passivation windows and separation of~~ separating the sensor chips produced on a semiconductor substrate (wafer). The mask serves, ~~to undercut~~ by a localized isotropic insulator etching process, ~~and to undercut and~~ completely separate from the insulating support, the ~~uppermost~~ portion of the conductor plane which in the completed sensor constitutes the resiliently moveable loop 3.

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Replacement Paragraph Page 12, Lines 1-6

This may be accomplished by the upper partial layer 10 of the intermediate insulator consisting of silicon dioxide or silicate glass and a lower partial layer 11 consisting of Si_3N_4 . The windows in the passivation layer 12 which also consist of Si_3N_4 , which have been structured with the above-mentioned additional lacquer resist mask prior to the isotropic undercutting, serve as an etching mask.

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